

SN74ALS232B

16 × 4 ASYNCHRONOUS FIRST-IN, FIRST-OUT MEMORY

SCAS251B – FEBRUARY 1989 – REVISED APRIL 1998

- Independent Asynchronous Inputs and Outputs
- 16 Words by 4 Bits
- Data Rates up to 40 MHz
- Fall-Through Time 14 ns Typical
- 3-State Outputs
- Package Options Include Plastic Small-Outline Package (DW), Plastic Chip Carriers (FN), and Standard Plastic 300-mil DIPs (N)

description

This 64-bit memory features high speed and fast fall-through times. It is organized as 16 words by 4 bits.

A first-in, first-out (FIFO) memory is a storage device that allows data to be written into and read from its array at independent data rates. This FIFO is designed to process data at rates up to 40 MHz in a bit-parallel format, word by word.

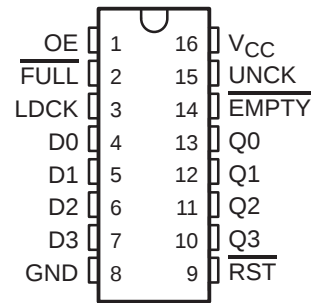
Data is written into memory on a low-to-high transition at the load-clock (LDCK) input and is read out on a low-to-high transition at the unload-clock (UNCK) input. The memory is full when the number of words clocked in exceeds by 16 the number of words clocked out. When the memory is full, LDCK signals have no effect on the data residing in memory. When the memory is empty, UNCK signals have no effect.

Status of the FIFO memory is monitored by the $\overline{\text{FULL}}$ and $\overline{\text{EMPTY}}$ output flags. The $\overline{\text{FULL}}$ output is low when the memory is full and high when it is not full. The $\overline{\text{EMPTY}}$ output is low when the memory is empty and high when it is not empty.

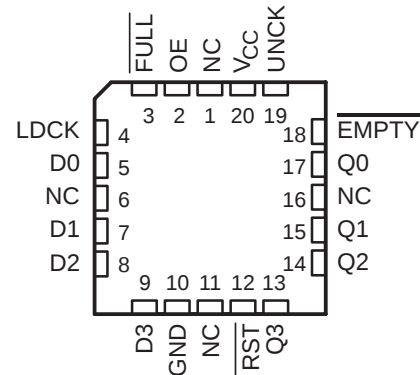
A low level on the reset ($\overline{\text{RST}}$) input resets the internal stack-control pointers and also sets $\overline{\text{EMPTY}}$ low and sets $\overline{\text{FULL}}$ high. The Q outputs are not reset to any specific logic level. The first low-to-high transition on LDCK, after either a $\overline{\text{RST}}$ pulse or from an empty condition, causes $\overline{\text{EMPTY}}$ to go high and the data to appear on the Q outputs. It is important to note that the first word does not have to be unloaded. Data outputs are noninverting with respect to the data inputs and are at high impedance when the output-enable (OE) input is low. OE does not affect the $\overline{\text{FULL}}$ or $\overline{\text{EMPTY}}$ output flags. Cascading is easily accomplished in the word-width direction but is not possible in the word-depth direction.

The SN74ALS232B is characterized for operation from 0°C to 70°C.

DW OR N PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



NC – No internal connection



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

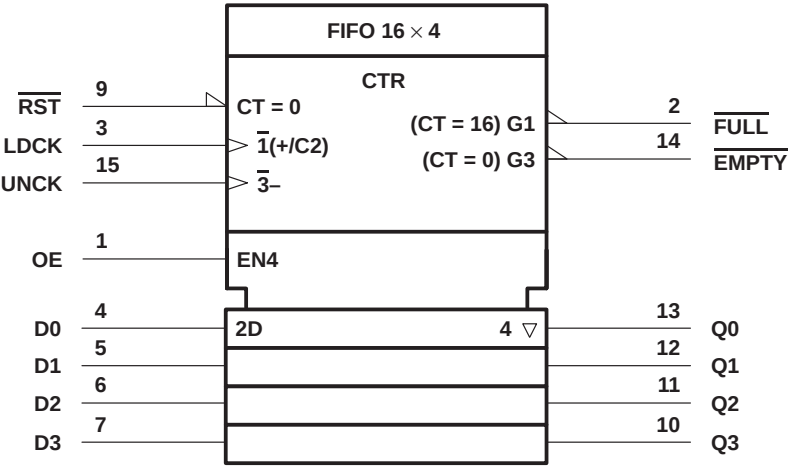
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logic symbol†



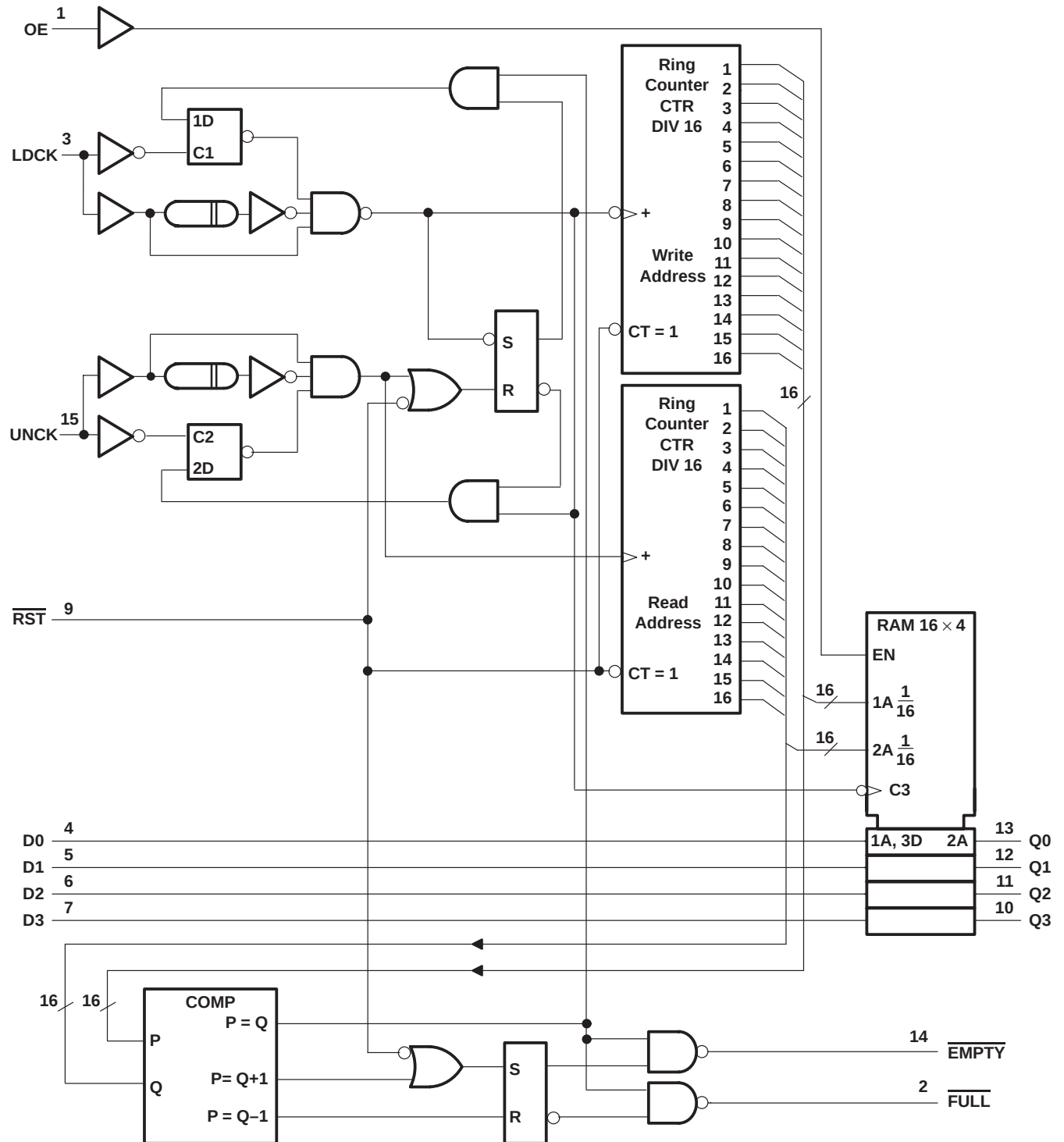
† This symbol is in accordance with ANSI/IEEE Standard 91-1984 and IEC Publication 617-12. The symbol is functionally accurate but does not show the details of implementation; for these, see the logic diagram. The symbol represents the memory as if it were controlled by a single counter whose content is the number of words stored at the time. Output data is invalid when the counter content (CT) is 0. Pin numbers shown are for the DW and N packages.

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logic diagram (positive logic)

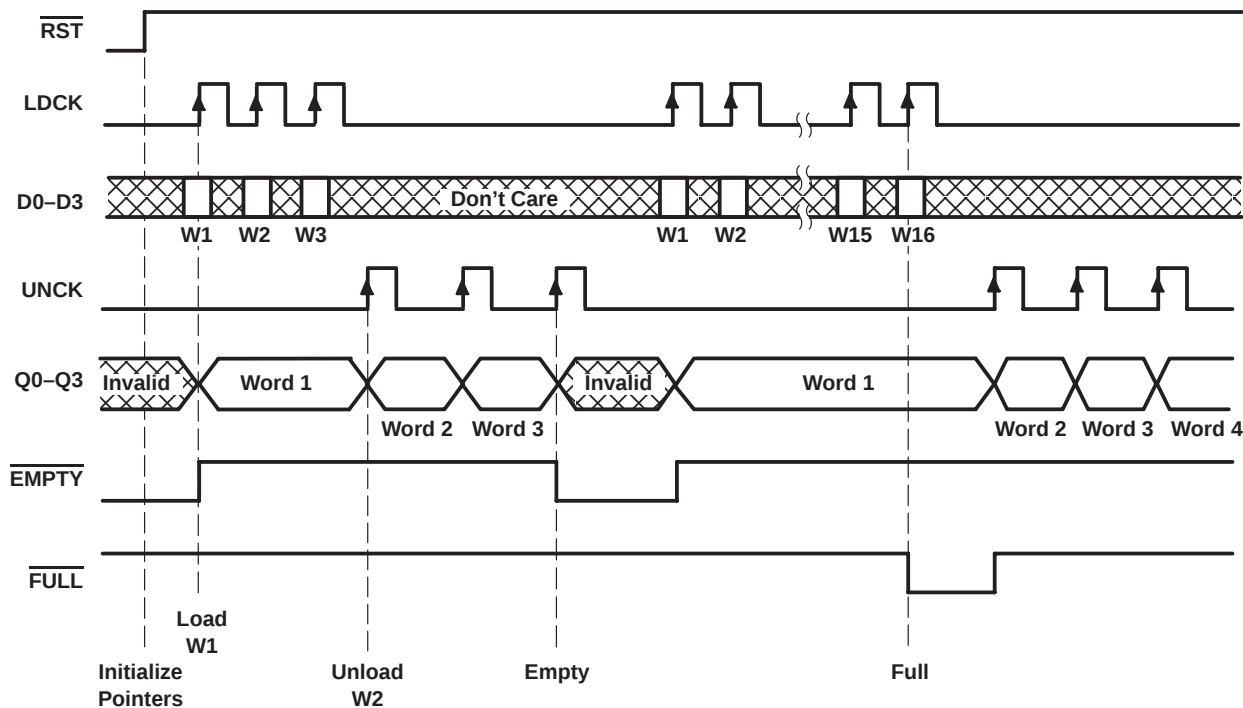


Pin numbers shown are for the DW and N packages.

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timing diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I	−0.5 V to 7 V
Voltage range applied to a disabled 3-state output	−0.5 V to 5.5 V
Package thermal impedance, θ_{JA} (see Note 2): DW package	105°C/W
FN package	83°C/W
N package	78°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those indicated in the “recommended operating conditions” section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to GND.
2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

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recommended operating conditions (see Note 3)

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
I _{OH}	High-level output current			–2.6	mA
				–0.4	
I _{OL}	Low-level output current			24	mA
				8	
T _A	Operating free-air temperature	0		70	°C

NOTE 3: To ensure proper operation of this high-speed FIFO device, it is necessary to provide a clean signal to the LDCK and UNCK clock inputs. Any excessive noise or glitching on the clock inputs that violates limits for maximum V_{IL}, minimum V_{IH}, or minimum pulse duration can cause a false clock or improper operation of the internal read and write pointers.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V,	I _I = –18 mA			–1.2	V
V _{OH}	Q outputs	V _{CC} = 4.5 V,	I _{OH} = –2.6 mA	2.4	3.2		V
	$\overline{\text{FULL}}, \overline{\text{EMPTY}}$	V _{CC} = 4.5 V to 5.5 V,	I _{OH} = –0.4 mA	V _{CC} – 2			
V _{OL}	Q outputs	V _{CC} = 4.5 V	I _{OL} = 12 mA		0.25	0.4	V
			I _{OL} = 24 mA		0.35	0.5	
	$\overline{\text{FULL}}, \overline{\text{EMPTY}}$	V _{CC} = 4.5 V	I _{OL} = 4 mA		0.25	0.4	
			I _{OL} = 8 mA		0.35	0.5	
I _{OZH}		V _{CC} = 5.5 V,	V _O = 2.7 V			20	μA
I _{OZL}		V _{CC} = 5.5 V,	V _O = 0.4 V			–20	μA
I _I		V _{CC} = 5.5 V,	V _I = 7 V			0.1	mA
I _{IH}		V _{CC} = 5.5 V,	V _I = 2.7 V			20	μA
I _{IL}		V _{CC} = 5.5 V,	V _I = 0.4 V			–0.2	mA
I _{O[‡]}		V _{CC} = 5.5 V,	V _O = 2.25 V	–30		–112	mA
I _{CC}		V _{CC} = 5.5 V			80	125	mA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

[‡] The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS}.

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timing requirements over recommended operating free-air temperature range (see Figure 1)

		MIN	NOM	MAX	UNIT
$f_{\text{clock}}^{\dagger}$ Clock frequency	LDCK			40	MHz
	UNCK			40	
t_w Pulse duration	$\overline{\text{RST}}$ low	18			ns
	LDCK low	15			
	LDCK high	10			
	UNCK low	15			
	UNCK high	10			
t_{su} Setup time	Data before LDCK $\uparrow$	8			ns
	LDCK inactive before $\overline{\text{RST}}\uparrow$	5			
t_h Hold time	Data after LDCK $\uparrow$	5			ns
	LDCK inactive after $\overline{\text{RST}}\uparrow$	5			

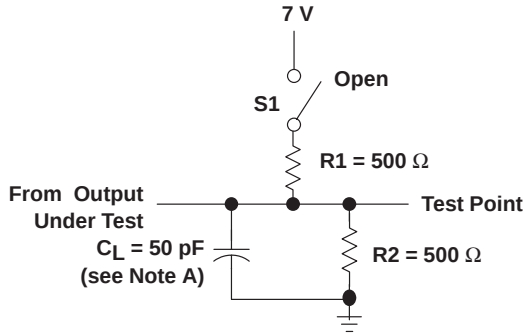
$\dagger$ The maximum possible clock frequency is 40 MHz. The maximum clock frequency when using a 50% duty cycle is 33.3 MHz.

switching characteristics (see Figure 1)

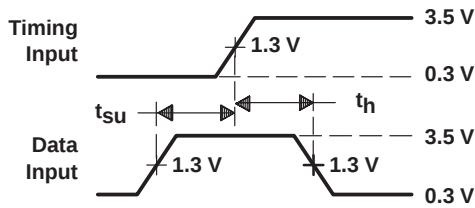
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	TYP ‡	MAX	MIN	MAX	UNIT
f_{max}	LDCK, UNCK			50		40		MHz
t_{pd}	LDCK $\uparrow$	Any Q		14	23	6	30	ns
	UNCK $\uparrow$			15	23	6	30	
t_{PLH}	LDCK $\uparrow$	$\overline{\text{EMPTY}}$		13	20	5	25	ns
t_{PHL}	UNCK $\uparrow$	$\overline{\text{EMPTY}}$		15	22	6	27	ns
	$\overline{\text{RST}}\downarrow$			15	21	5	26	
	LDCK $\uparrow$	$\overline{\text{FULL}}$		15	22	6	27	
t_{PLH}	UNCK $\uparrow$	$\overline{\text{FULL}}$		13	20	5	25	ns
	$\overline{\text{RST}}\downarrow$			16	23	7	28	
t_{en}	OE $\uparrow$	Q		5	12	1	14	ns
t_{dis}	OE $\downarrow$	Q		5	12	1	16	ns

$\ddagger$ Typical values at $V_{\text{CC}} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

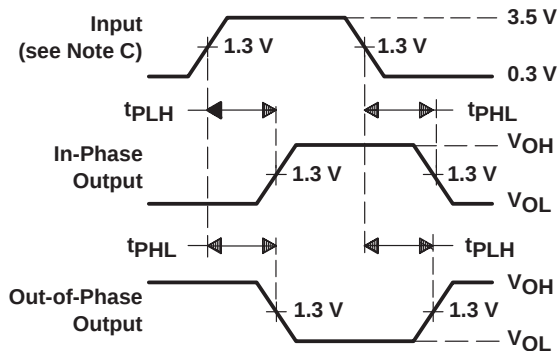
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR 3-STATE OUTPUTS



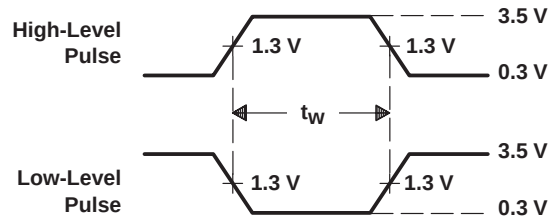
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



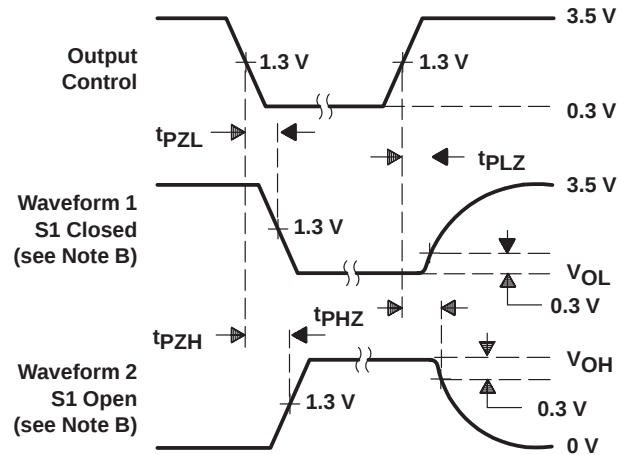
VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

SWITCH POSITION TABLE

PARAMETER	S1
t_{en}	t_{PZH} Open
	t_{PZL} Closed
t_{dis}	t_{PHZ} Open
	t_{PLZ} Closed
t_{pd}	t_{PLH} Open
	t_{PHL} Open



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_0 = 50 \Omega$, $t_r \leq 2 \text{ ns}$, $t_f \leq 2 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS232BDW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS232B	Samples
SN74ALS232BN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS232BN	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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GENERIC PACKAGE VIEW

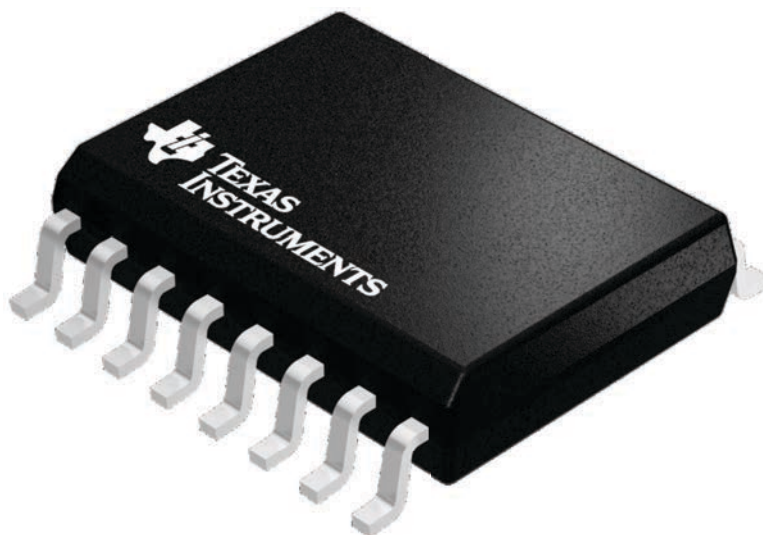
DW 16

SOIC - 2.65 mm max height

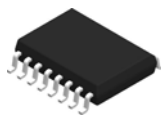
7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



4224780/A

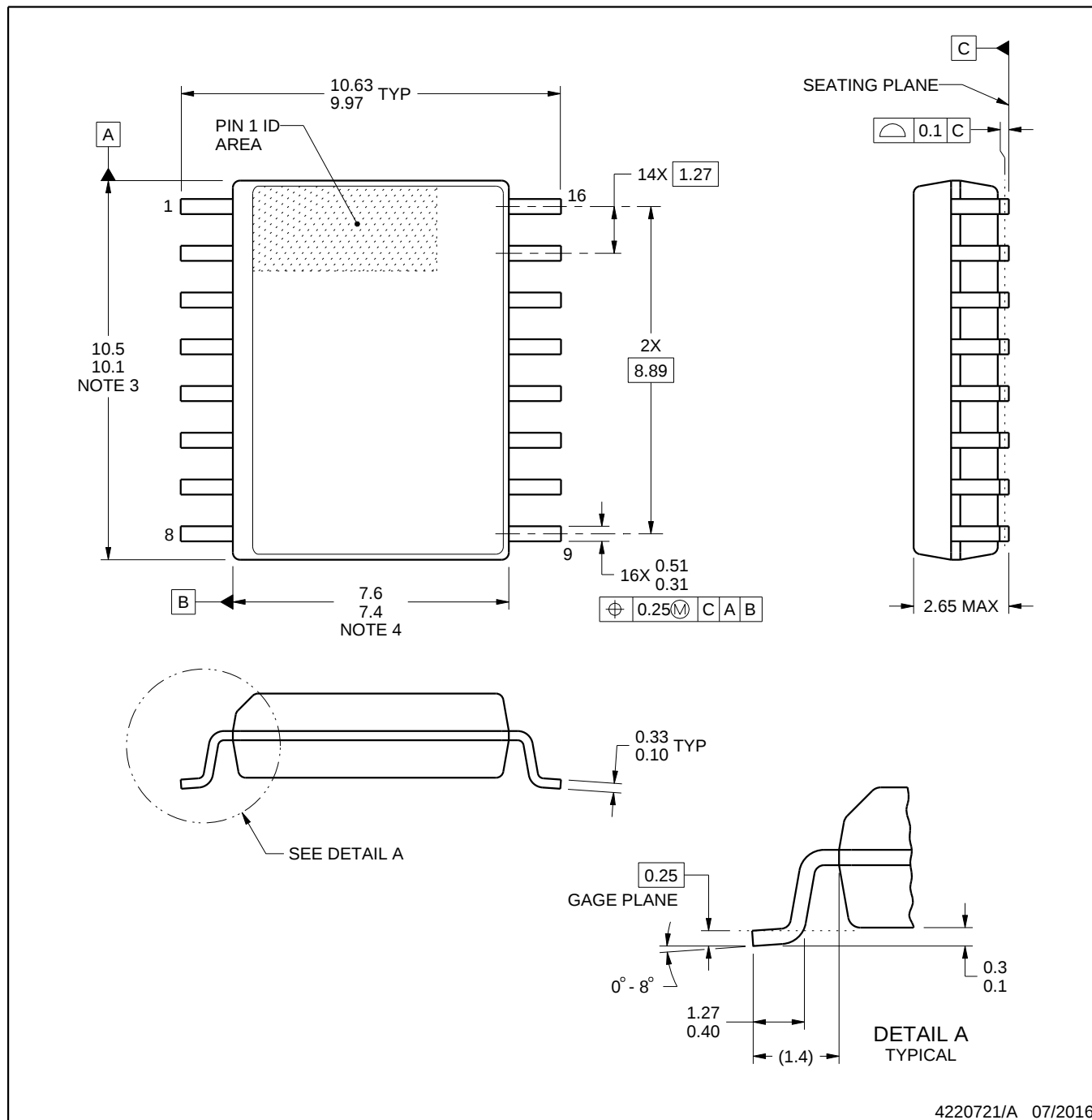


DW0016A

PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220721/A 07/2016

NOTES:

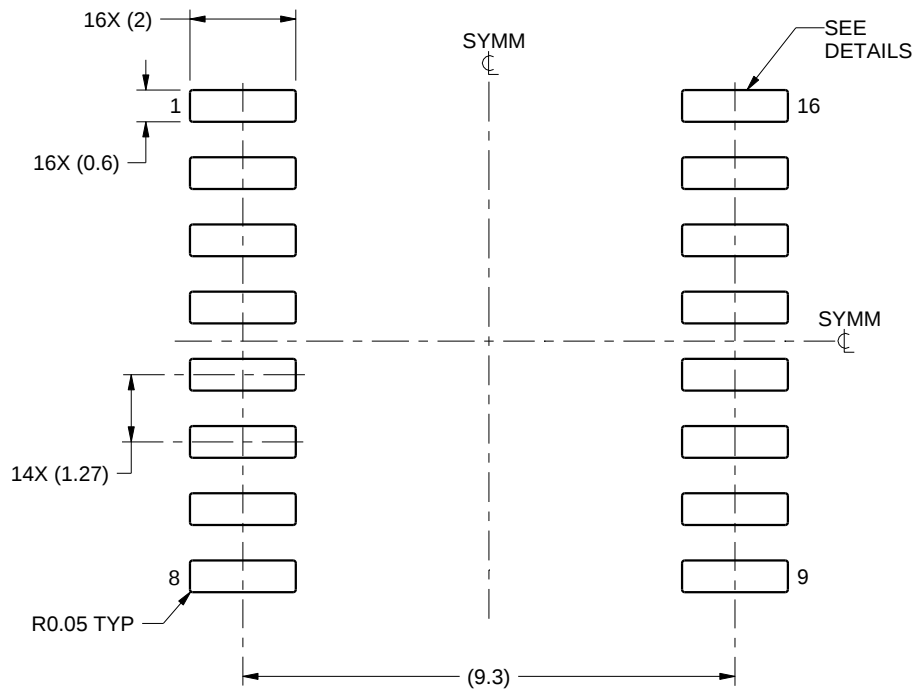
1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

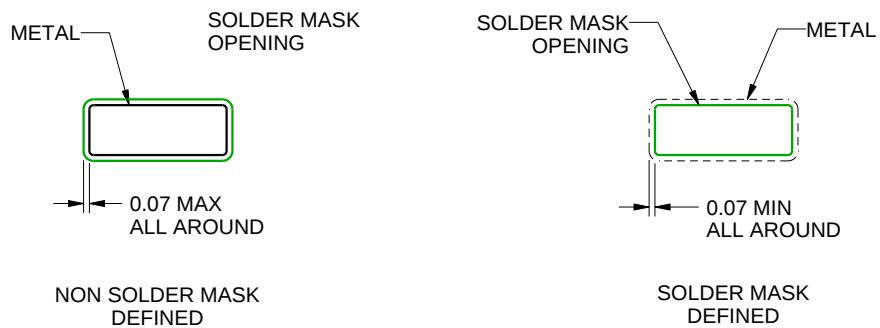
DW0016A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:7X



SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

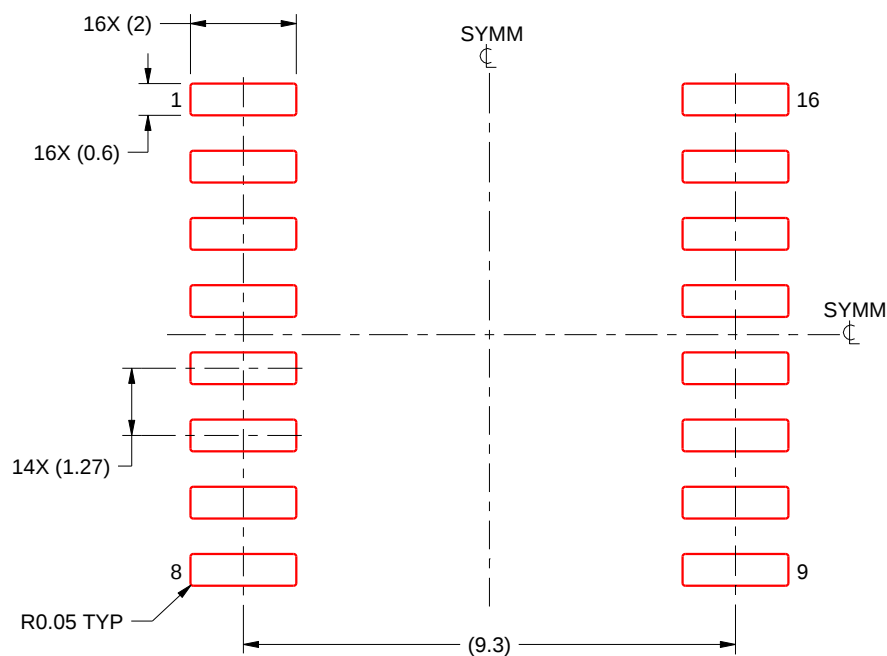
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0016A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220721/A 07/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 -  The 20 pin end lead shoulder width is a vendor option, either half or full width.

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